SuperBOT II:

- **High throughput：**High performance servo system, up to 1200 UPH for devices with programming time less than 36 sec. Throughput 0.6 to 30 times higher than SuperBot-1, especially higher for large capacity devices like eMMC, NAND /NOR FLASH,SPI FLASH. Suitable for both small and large capacity devices.**Accurate positioning：**Equipped with high performance servo system, precise CCD cameras for sockets / pick & place spots positioning
- **High performance programmers：**4 ultra-high speed universal gang programmers - SuperPro 7500. Each with up to 4 sockets, with a total of up to 16 sockets in the system
- **Varied I/O devices：**Supports tray, tape, tube input and output, laser and ink marking, and packing conversion. Can perform as a packing conversion machine alone
- **Short change-over time：**I/O devices and socket adaptor are easily interchangeable. Socket positioning can be performed automatically. Projects can be loaded automatically with barcode scanning
- **Powerful and intelligent software：**Setup data saved for next operation, log file and statistic reports available for quality assurance and traceability purposes, flexible sockets (with socket checking technology) convenient for unattended operation, graphical user interface cuts learning curve
- **Remote Control：**Remote project loading, quality monitoring, volume control, file security
- Built-in Industrial PC with OS Windows XP, 19” LCD display, keyboard and mouse. Communication interface: USB and LAN

I/O Devices

- **Manual Tray (Standard equipped)** One tray each time. Change tray manually.
- **Tape-out Device** Heat sealing and pressure sealing modes. Tape width adjustable between 8 and 32mm.
- **Tape-In Device** YAMAHA pneumatic feeder. Tape width between 8 and 32mm applicable.
- **Auto Tray Device** Moves blank tray in and passed tray out the machine automatically, marking the tray (optional). Stack up to 15 JEDEC trays.

- **Tube-In Device** Moves chips in the machine. Chip guider for different chip width (optional).
- **Tube-Out Device** Moves chips out the machine. Chip guider for different chip width (optional).
- **Tape Ink-Marker** An attachment to the tape-out device. Put a ink dot on the chip.
- **Auto Tray Ink-Marker** An attachment to the auto tray device. Scan and put dots on the passed chips.
- **Laser-Marker** An optional attachment to the tape-out or the auto tray device. Marks up to 4 characters on the passed chips.

Motion System

- **High precision servo drive system**
- **Resolution:** X axis**:** ±0.02mm ；Y axis：±0.02mm ；Z axis：±0.02mm; θaxis: ±0.1°
- Stroke： X axis：1000mm ；Y axis：500mm ；Z axis：40mm
- Pick & Place header accuracy：±0.07mm
- Operable chip size: min: 2x2mm; max: 25x25mm
- Maximum throughput：1200 UPH

Vision Systsem

- Downward CCD camera for sockets / pick & place spots positioning. 512×512 pixels
- Field of view：30mmX30mm
- Vision accur

Hardware & electrical Specifications

- **Devices Supported**: EPROM, Paged EPROM, Parallel and Serial EEPROM, FPGA Configuration PROM, FLASH memory (NOR & NAND), BPROM, NVRAM, SPLD, CPLD, EPLD, Firmware HUB, Microcontroller, MCU, etc...
- **Package**: DIP, SDIP, PLCC, JLCC, SOIC, QFP, TQFP, PQFP, VQFP, TSOP, SOP, TSOPII, PSOP, TSSOP, SON, EBGA, FBGA, VFBGA, uBGA, CSP, SCSP, ...
- **Power supply**: AAC 200 ~ 240V/50 ~ 60Hz, single phase
- **Power consumption**: 1.5KVA
- **Air:** Clean, pressure：0.6MPa, consumption：30 liter/min
- **Size:**
- **Main machine:** 820(L)×640(W)×1550(H)
- **Auto tray：** 1100（L）×380(W)×1300(H)
- **Tape-out**： 1100(L)×380(W)×1300(H)
- **Weight (Kg): Main machine:** 248 Kg